

# **ZTX749**

### **PNP Low Saturation Transistor**

· This device are designed with high current gain and low saturation voltage with collector currents up to 2A continuous.



# Absolute Maximum Ratings TA=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>CEO</sub>	Collector-Emitter Voltage	-25	V
V <sub>CBO</sub>	Collector-Base Voltage	-35	V
V <sub>EBO</sub>	Emitter-Base Voltage	-5	V
I <sub>C</sub>	Collector Current - Continuous	-2	Α
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range	-55 ~ +150	°C

<sup>\*</sup> These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- These ratings are based on a maximum junction temperature of 150°C.
   These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

# Electrical Characteristics T<sub>A</sub>=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Max.	Units
Off Characteristics					
BV <sub>CEO</sub>	Collector-Emitter Breakdown Voltage	I <sub>C</sub> = -10mA	-25		V
BV <sub>CBO</sub>	Collector-Base Breakdown Voltage	$I_{C} = -100 \mu A$	-35		V
BV <sub>EBO</sub>	Emitter-Base Breakdown Voltage	$I_E = -100 \mu A$	-5		V
I <sub>CBO</sub>	Collector Cutoff Current	V <sub>CB</sub> = -30V V <sub>CB</sub> = -30V, T <sub>A</sub> = 100°C		-100 -10	nA μA
I <sub>EBO</sub>	Emitter Cutoff Current	V <sub>EB</sub> = -4V		-100	nA
On Characteristics*					
h <sub>FE</sub>	DC Current Gain	$I_{C} = -50 \text{mA}, V_{CE} = -2 \text{V}$ $I_{C} = -1 \text{A}, V_{CE} = -2 \text{V}$ $I_{C} = -2 \text{A}, V_{CE} = -2 \text{V}$ $I_{C} = -6 \text{A}, V_{CE} = -2 \text{V}$	70 100 75 15	300	
V <sub>CE</sub> (sat)	Collector-Emitter Saturation Voltage	$I_C = -1A$ , $I_B = -100mA$ $I_C = -2A$ , $I_B = -200mA$		-300 -500	mV
V <sub>BE</sub> (sat)	Base-Emitter Saturation Voltage	$I_C = -1A, I_B = -100mA$		-1.25	V
V <sub>BE</sub> (on)	Base-Emitter On Voltage	I <sub>C</sub> = -1A, V <sub>CE</sub> = -2V		-1	V
Small-Sig	nal Characteristics	•	•		•
C <sub>obo</sub>	Output Capacitance	V <sub>CB</sub> = -10V, I <sub>E</sub> = 0, f = 1MHz		100	РF
f <sub>T</sub>	Transition Frequency	$I_C = 1-00 \text{mA}, V_{CE} = -5V$ f = 100MHz	100		

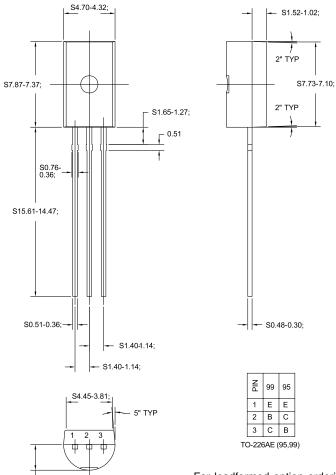
<sup>\*</sup> Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%

### Thermal Characteristics TA=25°C unless otherwise noted

Symbol	Parameter	Max.	Units
$P_{D}$	Total Device Dissipation	1	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	125	°C/W

# **Package Dimensions**

# TO-226



For leadformed option ordering, refer to Tape & Reel data information.

Dimensions in Millimeters

S2.41-2.13;

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Rev. I3

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### **Definition of Terms**

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